ABSTRACT OF THE DISCLOSURE

METHODS AND APPARATUS FOR ALIGNING AN INTEGRATED CIRCUIT PACKAGE WITH AN INTERFACE

An integrated circuit package (100) is provided with alignment pads (500, 502) which are solid or annular ring shaped. Alignment members such as balls (700, 1100) or bullets (800, 1300) are attached to the alignment pads via a wetting media (702, 802, 1102, 1302). When heated, the wetting media serves to center and seat the alignment members on the alignment pads. When cooled, the wetting media serves to bond the alignment members to the alignment pads.

FIG. 9A